# P-type Silicon irradiated with 24 GeV/c protons

Vladimir Cindro<sup>1</sup>, G. Kramberger<sup>1</sup>,I. Mandić<sup>1</sup>, M. Mikuž<sup>1,2</sup>, M. Zavrtanik<sup>1</sup> 1-Jožef Stefan Institute, Ljubljana, Slovenia 2-Department of Physics, University of Ljubljana, Slovenia

## Outline

- p-type Si serious candidate for trackers at LHC upgrade
- CCE depends on trapping. High E field, short drift length, proper readout side (electron signal dominates on nstrips) can reduce the effect of trapping on CCE
- p-type microstrip detectors with n-side readout have shown good performance after irradiation to high fluences

### **Description of silicon detectors**

- Diodes n+-p-p+. Characteristics:
- active area: 5×5 mm2
- substrates:
- Silicon <100>; 300 ± 15 μm; 20kΩ·cm
- DOFZ <100>; 300 ± 15 μm; 20kΩ·cm, [O]~2\*10<sup>17</sup>
- MCZ <100>; 300 ± 15  $\mu$ m; 5 kΩ·cm , [O]~5\*10<sup>17</sup>
- guard ring: 200 µm wide at 100 µm distance from the central diode
- n+-p junction depth: 2 μm
- P concentration on surface: 2.10<sup>19</sup> cm<sup>-3</sup>
- p+-n junction depth: 1.5 μm
- B concentration on backside surface: 10<sup>20</sup> cm<sup>-3</sup>
- Total dimensions of the device: 7.11×7.11 mm<sup>2</sup>
- Isolation: p-spray blanket, depth~2um, peak=10<sup>15</sup>cm<sup>-2</sup>





#### Fabrication procedure (CNM Barcelona)

- Summary of fabrication steps:
- Thick oxide growth (1 µm)
- Oxide patterning
- N+ implant
- Backside P+ implant
- Implant annealing (950°C, 30 min)
- Contact opening
- Metal deposition and patterning
- Metal annealing (350°C, 30 min)

#### Irradiations:

- Irradiations with 24 GeV/c protons at CERN
- Samples kept cool to prevent annealing

# Fluence dependence of N<sub>eff</sub>: p

**Protons** 

CV Measurements taken after 3 weeks at 20°C (approxim. "stable" damage)



#### **Neutrons**

If  $\Delta N_{eff}$  = g  $\Phi_{eq} \rightarrow g \sim 1.05 \ 10^{-2} \ cm^{-1}$ 

g ~ 2 10<sup>-2</sup> cm<sup>-1</sup>

CERN measur. 0.75 10<sup>-2</sup>cm<sup>-1</sup> (last workshop)

## Annealing of N<sub>eff</sub>:

Slopes:

Proton irradiated,  $\Phi_{eq}^{=}$  1.95 10<sup>14</sup> cm<sup>-2</sup>



Annealing at  $60^{\circ}C \rightarrow activation energy 1.25 \pm 0.05 eV$ 

## Determination of $t_{eff,e,h}$ – Charge correction method (I)



## Determination of $t_{eff,e,h}$ (II) – Charge correction method (II)



Charge increases with V for  $V > V_{fd}$  !

#### Measured

$$I_{m}(t) = I_{e,h}(t) = \left[e_{0} N_{e,h} \frac{1}{D} v_{e,h}(t)\right] \exp(\frac{-t}{\tau_{eff,e,h}})$$
  
Corrected  
$$I_{c}(t) = I_{m}(t) \exp(\frac{t-t_{0}}{\tau_{tr}})$$

 $Q_c$ =constant for  $V>VFD \longrightarrow \tau_{tr}=\tau_{eff}$ (without trapping the signal of fully depleted detector doesn't depend on voltage)

## **Integral of signal**

Hole signal

**Electron signal** 



Bulk remains p-type

# Trapping after annealing aq 60°C, measured at 20°C

Protons  $Φ_{eq}$  = 1.07 10<sup>14</sup> cm<sup>-2</sup> 1/τ = βΦ<sub>eq</sub>



1000 min at 60°C  $\rightarrow$  80 days at 20°C if E<sub>a</sub>= 1.0 eV

# Trapping after annealing at 60°C, measured at 20°C (neutrons)



1000 min at 60°C  $\rightarrow$  80 days at 20°C if E<sub>a</sub>= 1.0 eV

## Summary

- long term annealing of N<sub>eff</sub> in p-type material has same slope as in n-type
- activation energy is  $1.25 \pm 0.05$  eV.
- protons produce about 40% more trapping than neutrons at same NIEL
- Trapping in in p-type silicon similar to trapping in n-type also after proton irradiation
- beneficial annealing of e-trapping not as evident as with neutron irradiated samples (annealing before the measurements started)
- harmfull annealing of h-trapping

#### FDV during annealing Pad detectors irradiated to 10<sup>14</sup>cm<sup>-2</sup>



